

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L11	226	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and seal\$3 and chromium and copper	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:02
L12	96	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and seal\$3 and chromium and copper and (display adj1 device)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:02
L13	68	361/760 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
L14	14	361/751 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
L15	28	361/761 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
L16	6	361/765 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:55
L17	26	361/767 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:56
L18	10	361/768 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:56
L19	11	361/772 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:57
L20	57	313/504 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:57

L21	5581	313/5046and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
L22	75	313/506 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
L23	38	313/509 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
L24	6	313/510 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
L25	21	313/511 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
L26	37	313/512 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:58
S1	320	glass near (substrate or board) and (vias or (through near holes)) and filler	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 19:38
S63	82	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler and chromium and copper	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/19 19:01
S64	8	"5814935"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 19:38
S65	25	"5319159"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:19

S66	5	"5559399"	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:22
S67	164	(levi adj1 dameon)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:23
S68	589	"361"/\$.ccls. and (gandhi adj1 jayprakash)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:30
S69	836	(gandhi adj1 jayprakash)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/07/18 20:30